## TPC6006-H

## Notebook PC Applications

## Portable Equipment Applications

- Small footprint due to small and thin package
- High-speed switching
- Small gate charge: Qsw $=2.4 \mathrm{nC}$ (typ.)
- Low drain-source ON-resistance: $\mathrm{RDS}(\mathrm{ON})=59 \mathrm{~m} \Omega$ (typ.)
- High forward transfer admittance: $\left|\mathrm{Y}_{\mathrm{fs}}\right|=7 \mathrm{~S}$ (typ.)
- Low leakage current: $\mathrm{I}_{\mathrm{DSS}}=10 \mu \mathrm{~A}(\max )\left(\mathrm{V}_{\mathrm{DS}}=40 \mathrm{~V}\right)$
- Enhancement mode: $\mathrm{V}_{\mathrm{th}}=1.1$ to $2.3 \mathrm{~V}(\mathrm{VDS}=10 \mathrm{~V}, \mathrm{ID}=1 \mathrm{~mA})$


## Absolute Maximum Ratings ( $\mathbf{T a}=\mathbf{2 5}{ }^{\circ} \mathrm{C}$ )

| Characteristics | Symbol | Rating | Unit |
| :---: | :---: | :---: | :---: |
| Drain-source voltage | $V_{\text {DSS }}$ | 40 | V |
| Drain-gate voltage ( $\left.\mathrm{R}_{\mathrm{GS}}=20 \mathrm{k} \Omega\right)$ | VDGR | 40 | V |
| Gate-source voltage | $V_{G S S}$ | $\pm 20$ | V |
| Drain current | ID | 3.9 | A |
|  | IDP | 15.6 |  |
| $\begin{array}{lr}\text { Drain power dissipation } & (\mathrm{t}=5 \mathrm{~s}) \\ (\text { Note } 2 \mathrm{a})\end{array}$ | PD | 2.2 | W |
| $\begin{array}{lr}\text { Drain power dissipation } & \begin{array}{r}(t=5 \mathrm{~s}) \\ (\text { Note } 2 \mathrm{~b})\end{array}\end{array}$ | PD | 0.7 | W |
| Single pulse avalanche energy <br> (Note 3) | $\mathrm{EAS}_{\text {AS }}$ | 7 | mJ |
| Avalanche current | $\mathrm{I}_{\text {AR }}$ | 3.9 | A |
| Repetitive avalanche energy (Note 4) | $\mathrm{EAR}_{\text {AR }}$ | 0.22 | mJ |
| Channel temperature | $\mathrm{T}_{\mathrm{ch}}$ | 150 | ${ }^{\circ} \mathrm{C}$ |
| Storage temperature range | $\mathrm{T}_{\text {stg }}$ | -55 to 150 | ${ }^{\circ} \mathrm{C}$ |



Weight: 0.011 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/ "Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

## Thermal Characteristics

| Characteristics | Symbol | Max | Unit |
| :---: | :---: | :---: | :---: |
| Thermal resistance, channel to ambient ( $\mathrm{t}=5 \mathrm{~s}$ ) <br> (Note 2a) | $\mathrm{R}_{\text {th }}$ (ch-a) | 56.8 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| Thermal resistance, channel to ambient ( $\mathrm{t}=5 \mathrm{~s}$ ) <br> (Note 2b) | $\mathrm{R}_{\text {th }}$ (ch-a) | 178.5 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |

Note: (Note 1), (Note 2), (Note 3), (Note 4) and (Note 5): See the next page.

## Circuit Configuration



This transistor is an electrostatic-sensitive device. Handle with care.

## Marking (Note 5)



Electrical Characteristics ( $\mathrm{Ta}=\mathbf{2 5 ^ { \circ }} \mathbf{C}$ )

| Characteristics |  | Symbol | Test Condition | Min | Typ. | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Gate leakage current |  | IGSS | $\mathrm{V}_{\mathrm{GS}}= \pm 16 \mathrm{~V}, \mathrm{~V}_{\mathrm{DS}}=0 \mathrm{~V}$ | - | - | $\pm 10$ | $\mu \mathrm{A}$ |
| Drain cut-OFF current |  | IDSS | $\mathrm{V}_{\mathrm{DS}}=40 \mathrm{~V}, \mathrm{~V}_{\mathrm{GS}}=0 \mathrm{~V}$ | - | - | 10 | $\mu \mathrm{A}$ |
| Drain-source breakdown voltage |  | $V_{\text {(BR) }}$ DSS | $\mathrm{I}_{\mathrm{D}}=10 \mathrm{~mA}, \mathrm{~V}_{\mathrm{GS}}=0 \mathrm{~V}$ | 40 | - | - | V |
|  |  | $V_{\text {(BR) }}$ DSX | $\mathrm{I}_{\mathrm{D}}=10 \mathrm{~mA}, \mathrm{~V}_{\mathrm{GS}}=-20 \mathrm{~V}$ | 25 | - | - |  |
| Gate threshold voltage |  | $\mathrm{V}_{\text {th }}$ | $\mathrm{V}_{\mathrm{DS}}=10 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=1 \mathrm{~mA}$ | 1.1 | - | 2.3 | V |
| Drain-source ON resistance |  | $\mathrm{R}_{\mathrm{DS}}(\mathrm{ON})$ | $\mathrm{V}_{\mathrm{GS}}=4.5 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=1.9 \mathrm{~A}$ | - | 78 | 100 | $\mathrm{m} \Omega$ |
|  |  | $\mathrm{V}_{\mathrm{GS}}=10 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=1.9 \mathrm{~A}$ | - | 59 | 75 |  |
| Forward transfer admittance |  |  | $\left\|\mathrm{Y}_{\mathrm{fs}}\right\|$ | $\mathrm{V}_{\mathrm{DS}}=10 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=1.9 \mathrm{~A}$ | 3.5 | 7 | - | S |
| Input capacitance |  | Ciss | $\mathrm{V}_{\mathrm{DS}}=10 \mathrm{~V}, \mathrm{~V}_{\mathrm{GS}}=0 \mathrm{~V}, \mathrm{f}=1 \mathrm{MHz}$ | - | 251 | - | pF |
| Reverse transfer capacitance |  | Crss |  | - | 18 | - |  |
| Output capacitance |  | Coss |  | - | 73 | - |  |
| Switching time | Rise time | $\mathrm{t}_{\mathrm{r}}$ | Duty $\leqq 1 \%, \mathrm{t}_{\mathrm{w}}=10 \mu \mathrm{~s}$ | - | 4 | - | ns |
|  | Turn-ON time | $\mathrm{t}_{\mathrm{on}}$ |  | - | 9 | - |  |
|  | Fall time | $t_{f}$ |  | - | 3 | - |  |
|  | Turn-OFF time | $\mathrm{t}_{\text {off }}$ |  | - | 18 | - |  |
| Total gate charge (gate-source plus gate-drain) |  | $\mathrm{Q}_{\mathrm{g}}$ | $\mathrm{V}_{\mathrm{DD}} \simeq 32 \mathrm{~V}, \mathrm{~V}_{\mathrm{GS}}=10 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=3.9 \mathrm{~A}$ | - | 4.4 | - | nC |
|  |  | $\mathrm{V}_{\mathrm{DD}} \simeq 32 \mathrm{~V}, \mathrm{~V}_{\mathrm{GS}}=5 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=3.9 \mathrm{~A}$ | - | 2.4 | - |  |
| Gate-source charge 1 |  |  | $\mathrm{Q}_{\mathrm{gs} 1}$ | $\mathrm{V}_{\mathrm{DD}} \simeq 32 \mathrm{~V}, \mathrm{~V}_{\mathrm{GS}}=10 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=3.9 \mathrm{~A}$ | - | 1.0 |  | - |
| Gate-drain ("Miller") charge |  | $\mathrm{Q}_{\mathrm{gd}}$ | - |  | 0.8 | - |  |
| Gate switch charge |  | QSW | - |  | 1.3 | - |  |

## Source-Drain Ratings and Characteristics ( $\mathrm{Ta}=\mathbf{2 5}{ }^{\circ} \mathrm{C}$ )

| Characteristics | Symbol | Test Condition | Min | Typ. | Max | Unit |
| :--- | :--- | :---: | :---: | :---: | :---: | :---: |
| Pulse drain reverse current | (Note 1) | $I_{\mathrm{DRP}}$ | - | - | - | 15.6 |
| Forward voltage (Diode) |  | $\mathrm{V}_{\mathrm{DSF}}$ | $I_{\mathrm{DR}}=3.9 \mathrm{~A}, \mathrm{~V}_{\mathrm{GS}}=0 \mathrm{~V}$ | - | - | -1.2 |

Note 1: Ensure that the channel temperature does not exceed $150^{\circ} \mathrm{C}$.

Note 2: (a) Device mounted on a glass-epoxy board (a)

(a)
(b) Device mounted on a glass-epoxy board (b)

(b)

Note 3: $\mathrm{V}_{\mathrm{DD}}=24 \mathrm{~V}, \mathrm{~T}_{\mathrm{ch}}=25^{\circ} \mathrm{C}$ (initial), $\mathrm{L}=0.5 \mathrm{mH}, \mathrm{R}_{\mathrm{G}}=25 \Omega, \mathrm{I}_{\mathrm{AR}}=3.9 \mathrm{~A}$
Note 4: Repetitive rating: pulse width limited by maximum channel temperature Note 5: • on lower left of the marking indicates Pin 1.














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